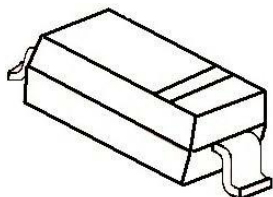




特征 Features

- 开关速度小于 4.0nS; Fast Switching Device (TRR <4.0 nS)
- 最大功率耗散 500mW; Power Dissipation of 500mW
- 高稳定性和可靠性。High Stability and High Reliability
- 反向漏电流小。Low reverse leakage

SOD-123



机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

MARKING: T4



极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
反向峰值电压 Peak Reverse Voltage	V _{RM}	100	V
功率消耗 Power Dissipation	P _d	500	mW
工作结温 Operating junction temperature	T _j	150	°C
存储温度 Storage temperature range	T _{STG}	-65-+150	°C
热阻 Thermal Resistance from Junction to Ambient	R _{θJA}	250	°C/W
平均整流电流 Average Rectified Current	I _o	150	mA
正向(不重复)电流 Non-repetitive Peak Forward Current	I _{FM}	300	mA
正向(不重复)浪涌电流 Peak Forward Surge Current @tp=1us; TA=25°C	I _{FSM}	2.0	A

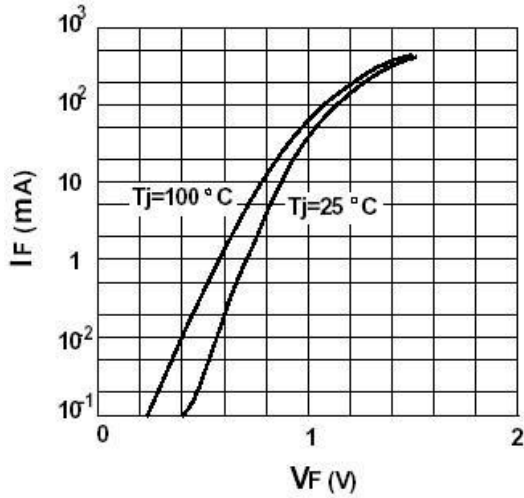
Valid provided that electrodes are kept at ambient temperature.

电特性 Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

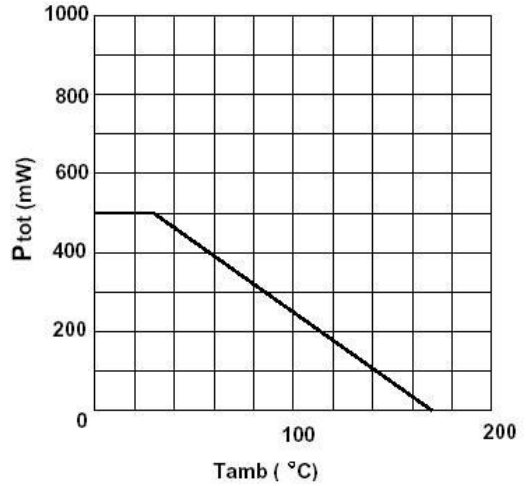
符号 Symbols	参数 Parameter	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
BV	反向击穿电压 Breakdown Voltage	IR=100uA	100		V
IR	反向漏电流 Reverse Leakage Current	VR=20V	---	25	nA
		VR=20V Tj=150°C	---	50	uA
		VR=75	---	5	uA
VF	正向电压 Forward Voltage	IF=10mA	---	1.00	V
		IF=100mA	---	1.25	
TRR	反向恢复时间 Reverse Recovery Time	IF = IR = 10mA, Irr=0.1XIR RL=100Ω	---	4	nS
C	结电容 Capacitance	VR=0V, f=1MHZ	---	4	pF



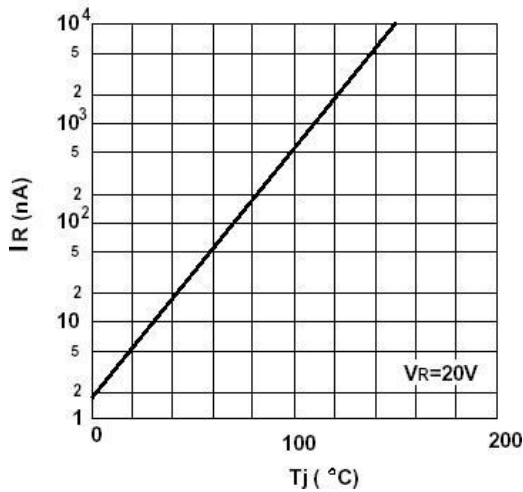
Forward characteristics



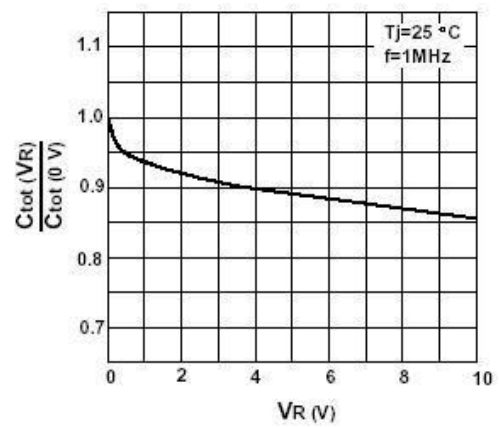
Admissible power dissipation versus ambient temperature



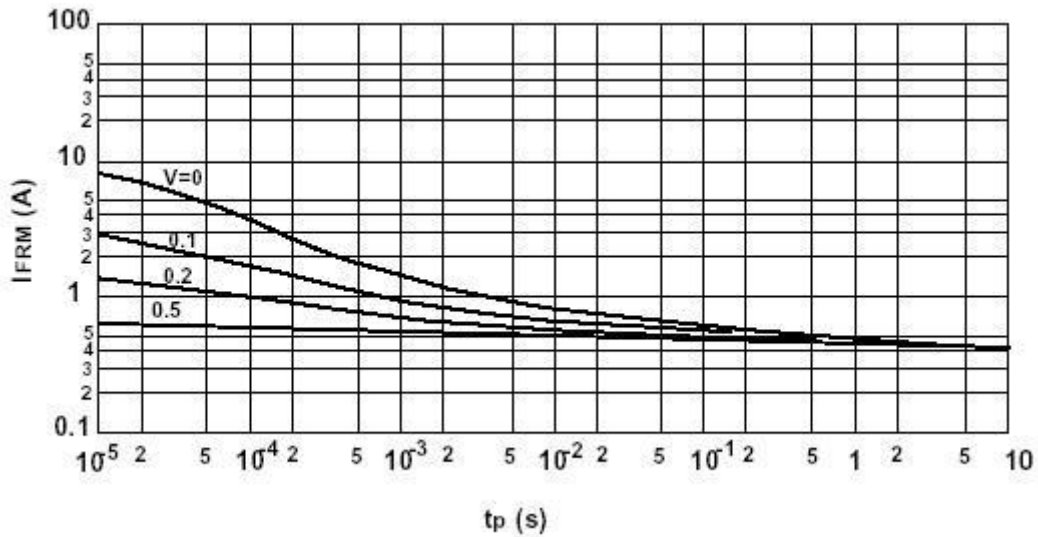
Leakage current versus junction temperature



Reverse capacitance VS. reverse voltage

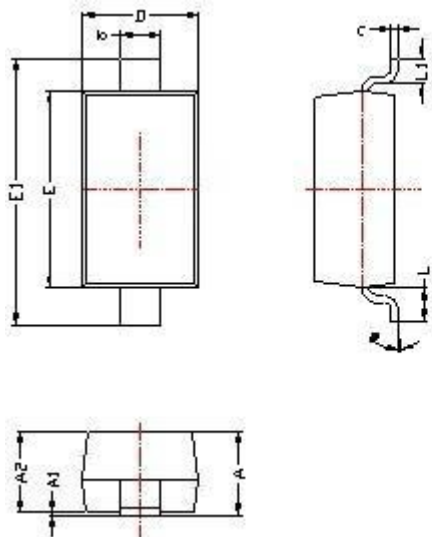


Admissible repetitive peak forward current VS. pulse duration



SOD-123 PACKAGE OUTLINE

Plastic surface mounted package

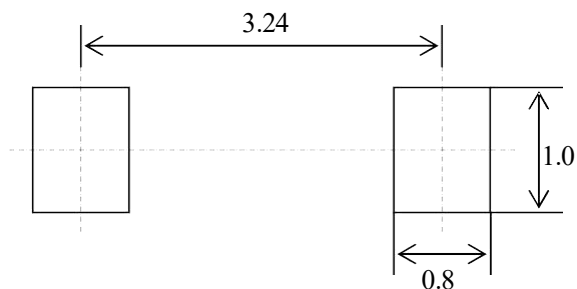


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



中心距: 3.24
脚宽: 0.55
焊盘宽: 1.00
脚长: 0.50
焊盘长: 0.80

技术要求:

- 1, 塑封体尺寸: 2.70 X 1.60
- 2, 未注公差为: ± 0.05

3, 所有单位: mm